P	CN Number:	20231023000.2								PCN Date:		October 23, 2023		
Т	itle:	Adding DMOS4 & TIEM-PR as additional wafer probe (EWS) site												
C	ustomer Contact:		Change Management team Dept: (Qι	Quality Services				
P	roposed 1 st Ship Da	te: Jan 24			, 2024				Sample requests accepted until:					
C	hange Type:													
Assembly Site						Design			Wat	Wafer Bump Site				
	Assembly Process					Data She	Data Sheet			Wat	Wafer Bump Material			
	Assembly Material						number change			_	Wafer Bump Process			
Mechanical Specific						Test Site				_	Wafer Fab Site			
Packing/Shipping/Labelin				☐ Test Prod			cess				Wafer Fab Materials			
										Wafer Fab Process				
	PCN Details													
D	Description of Change:													
Texas Instruments Incorporated has qualified DMOS4 $\&$ TIEM-PR as additional probe (EWS) site for the devices listed below to support high volume ramps.														
		Current:						New:						
	Probe Site (EW					D-PR)	DMOS4 (I				DL-MOS-4), TIEM-PR			
	2.1.35 G.16 (2.1.5) 1.1.62 1.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9 2.1.9													
Τ	Test coverage, insertions, conditions will remain consistent with current testing.													
R	Reason for Change:													
E	Enable additional probe capacity to support high volume ramps.													
A	Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):													
N	None.													
I	mpact on Environm	enta	ıl Rat	tings:										
	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.													
	RoHS			REAC	CH		Gre	en Statı	us		IEC 62	2474		
	☑ No Change		\bowtie N	o Chang	e		No C	Change		_ ⊠ N	lo Chan	ge		
C	Changes to product identification resulting from this PCN:													
Ν	None.													
P	Product Affected:													
	DRA821U4ERBALMQ1		DRAS	29JMT0	BAL	FQ1 D	RA82	9VMTGB	ALFQ	1 7	DA4VM	88TGBALFQ1		
	DRA821U4ERBALMRQ1			29JMT0			RA82	9VMTGB	ALFR			88TGBALFRQ1		
	DRA821U4T5BALMQ1						TDA4VM88T5BALFQ				TDA4VM88TRBALFQ1			
	DRA821U4T5BALMRQ1 DRA829JMT5I											88TRBALFRQ1		
	RA821U4TCBALMQ1 DRA829JMTG											· ·		
	DRA821U4TCBALMRO													

ZVEI ID reference: SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.